

Software Engineer Intern dedicated to improving skills through hands-on learning and development work. Proficient in VR development and HCI. Adept at using Unity(C#), Python, and other programming languages to produce clean code. Equipped with HCI research accomplishments and AI internship experience.

Awards and Fellowships

2023.04 - Current	Research Fellowship for Young Scientists DC2 [Acceptance rate: 18.5 %] Japan Society for the Promotion of Science
2022.05	3rd place in Demo Award, Eurohaptics2022 [International] Airborne Bumpy Surfaces Presented by Ultrasound
2021.12	Presentation Award, SICE SI 2021 [Domestic] Curved Surface Presentation using Airborne Ultrasound
2020.09 - Current	International Graduate Program of Innovation for Intelligent World [Acceptance rate: 48.1 %] The University of Tokyo

Selected Publications and Presentations

Research Article

2021.04	Fabrication of Eutectic Ga-In Nanowire Arrays Based on Plateau-Rayleigh Instability Takashi Ikuno, <u>Zen Somei</u> , MOLECULES, 26(15), 4616.
2023.12	Spatial Resolution of Mesoscopic Pattern via Contact Position Control using Airborne Ultrasound <u>Zen Somei</u> , Tao Morisaki, Shun Suzuki, Yasutoshi Makino, Hiroyuki Shinoda, Transactions on Haptics [Under Review]

Conference Proceedings (Oral Presentation)

2022.05	Spatial Resolution of Mesoscopic Shapes [Acceptance rate: 57.0 %] <u>Zen Somei</u> , Tao Morisaki, Yutaro Toide, Masahio Fujiwara, Yasutoshi Makino, Hiroyuki Shinoda, Eurohaptics 2022.
---------	--

Education and Internships

2022.04 - In Progress	Ph.D. in Complexity Science and Engineering The University of Tokyo
2022.10 - 2022.12	Internship in NEC Corporation Theme: Sequential Updating of Prediction Model Using Unscented Kalman Filter
2020.04 - 2022.03	M.S. in Complexity Science and Engineering The University of Tokyo
2016.04 - 2020.03	B.S. in Applied Electronics Tokyo University of Science

Contact

E-mail

somei@hapis.k.u-tokyo.ac.jp

LinkedIn

www.linkedin.com/in/zen-somei

Skills

C, C++, C#, Unity, Python,
R, VR development,
hand sensing.

Languages

Japanese, English, Chinese.

Interests

haptics, VR, AR, metaverse,
engineering, HCI, ultrasound.